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DICING EQUIPMENT IS THE HOTTEST ASSEMBLY EQUIPMENT SEGMENT

Santa Clara, CA, July 7, 2006: The dicing equipment market, which includes dicing saws, scribing tools, dicing accessories and backside grinding, has grown at a compounded annual growth rate (CAGR) of 31.4% since 2002. In contrast, the overall assembly equipment market grew 18% CAGR during the same period. The best performing Dicing segments were scribing tools and backside grinding, each averaging over 50% CAGR since 2002.

In 2005, sales of dicing equipment reached \$518.8M. DISCO was the leading supplier with a 44% market share, followed by ACCRETECH-Tokyo Seimitsu and Xsil Ltd. Sales of dicing equipment are expected to reach \$671M in sales by 2011.

The table below shows the Top 3 Dicing Equipment Suppliers in 2005:

The Top IC Dicing Equipment Suppliers - 2005
(worldwide sales by company, calendar year, \$M)

DISCO Corporation	228.2
ACCRETECH - Tokyo Seimitsu	157.0
Xsil Ltd.	30.4
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Total Market	518.8

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